

SEMICONDUCTOR WAFER LAMINATION TEST SOLUTION

PROJECT INTRODUCTION

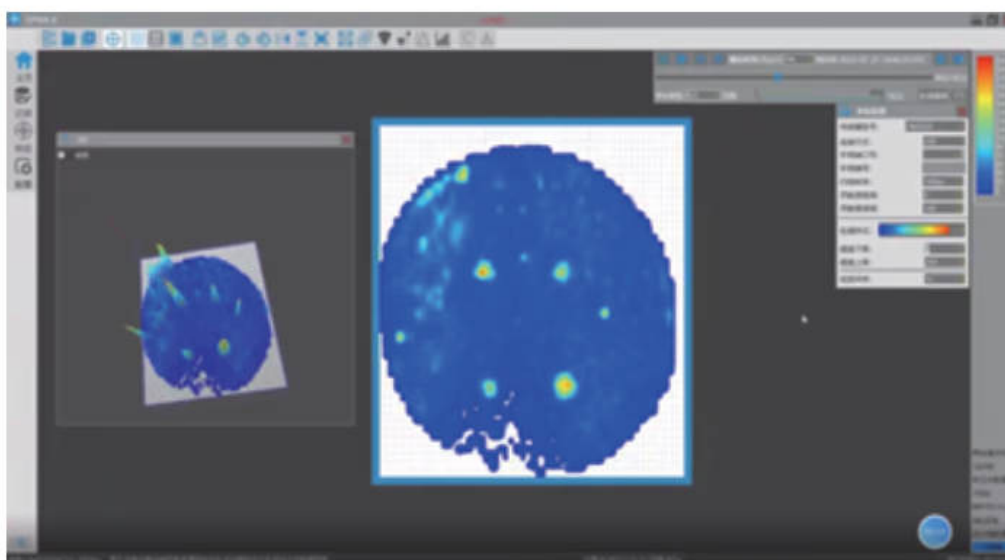
Along with the chip size is getting smaller and smaller, the wafer diameter is increasing, and the difficulty of multiple wafer lamination increases. In order to realize multi wafer lamination, the surface of the wafer must have extremely high flatness, smoothness and cleanliness. Customers need our pressure distribution measurement equipment to verify the parallelism of the wafer placement equipment during dispensing.



MEASURING METHOD

The sensor is placed between two wafers to simulate wafer lamination and test the pressure distribution during lamination to verify the parallelism of the wafer placement equipment.

MEASUREMENT RESULT



Through the test of our distributed pressure measurement system, customers intuitively and clearly understand the parallelism of the equipment, but also test the flatness of the wafer itself. Provide data reference for customers to upgrade equipment later.

USE

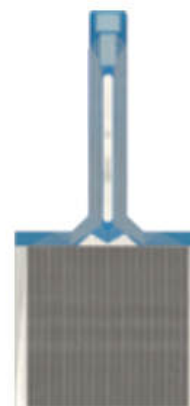
Product Design Verification
Equipment Flatness
Measurement

ADVANTAGES

Data visualization
Accurate measurement of
pressure distribution

EQUIPMENT: D2

General Purpose
Distributed Pressure
Measurement System
DPM-G



MODEL	CN2020
Sensing area	200mm *200mm
No. of sensing points	2288, 44rows*52columns
Point density	5.6points/cm ²
Pressure ranges	250psi